

DNP FID1
DNP FID2
DNP FID3

PCB Number: TIDA-00720
PCB Rev: A

PCB LOGO
Texas Instruments
PCB LOGO
Pb-Free Symbol
PCB LOGO
FCC disclaimer

PCB LOGO

Label Table	
Variant	Label Text
001	TIDA-00720

LBL1
PCB Label
Size: 0.65" x 0.20"

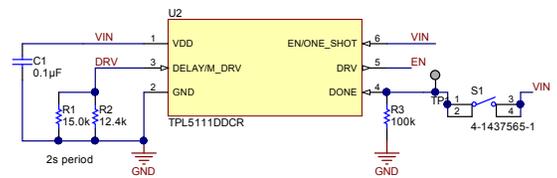
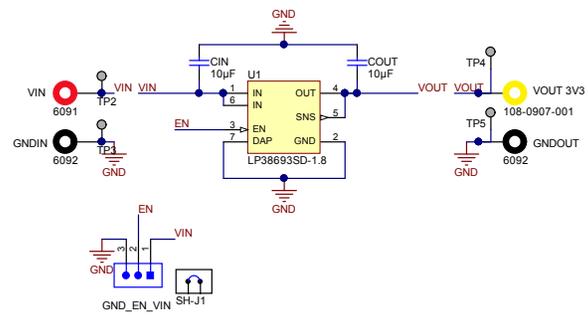
ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

ZZ5
Assembly Note
Place SH-J1 on pins 1 and 2 of GND_EN_IN header



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